Plans for FY08/09

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Current plan

- Assume a new proposal will be submitted ~Oct08
  - If approved, funding comes on-stream in Apr09, i.e. FY09/10 onwards
  - Proposal would be considered by PPRP Oct-Dec08
  - Approval or not known by Jan09
- Within FY08/09 need to continue until new funding available
  - Work between now and Nov08 should maximise probability of proposal being approved
  - Work after Nov08 should prepare ground for new proposal work
- For FY08/09, putting in bid to prevent immediate, complete cut
  - Will bid for funds to make a second sensor
  - If cut back, then will only test current sensor but in more detail than planned
- The main point in making the second sensor is to increase the chance of approving the proposal
  - Must be produced and tested by end of Nov08
  - Feed results into PPRP in Dec08
- A publication would also help a lot with the proposal approval

Implications

- Assume the second sensor needs at least three months of tests
  - This would be Sep-Nov inclusive
- The sensor needs two months to fabricate
  - This would be Jul-Aug inclusive
- The design needs to be submitted by the end of Jun
  - Needs one month for final simulations, checks, reviews, etc.
- Tests of first sensor must find problems and give input to the design
  - Need to be completed by end of May
- We also need to produce one (or more) publications
  - This should be within the next six months while effort available

Questions

- Can we complete all testing of first sensor needed for second sensor design within four months?
  - Do we have enough effort between now and May?
  - Testing can and will continue afterwards e.g. for a publication
- Can Jamie redesign the sensor by the end of Jun?
  - From last meeting, seems feasible but depends on what needs to be changed
  - What would we want the second sensor to look like?
  - How late could major issues be resolved e.g. a low efficiency?
- Can we complete all testing of second sensor in Sep-Nov?
  - Do we have enough effort remaining at that time?
  - Unfeasible for beam test? Test structures, sources, cosmics, laser?
  - Wafers with and without deep p-well?
- Minimise new components by reusing existing DAQ and sensor PCBs?
  - Would require new sensor to be PCB-compatible; can this be decided today?
  - If so, use FY07/08 funds to make ~30 more PCBs